



## IN THE UNITED STATES PATENT AND TRADEMARK OF

Applicant:

Hunt Hang Jiang, et al.

Confirmation No.:4925

Serial No.:

09/834,273

Filed:

April 12, 2001

For:

STRUCTURE AND METHOD FOR DEPOSITING SOLDER

**BUMPS ON A WAFER** 

Art Group Unit:

2823

Examiner:

Deven M. Collins

Attorney Docket: 25916-194 (6136/53945)

## **CERTIFICATE OF** MAILING/TRANSMISSION (37 C.F.R. § 1.8A)

I hereby certify that this correspondence is, on the date shown below, being:

(X) deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231.

( ) transmitted by facsimile to the Patent and Trademark Office

August 5, 2002

## RESPONSE TO RESTRICTION REQUIREMENT

Commissioner for Patents Washington, D.C. 20231

Dear Sir:

This is in response to the Restriction Requirement mailed on June 3, 2002. This response is timely with the automatic entry of the accompanying Petition for Extension of time.

Applicants elect Claims 1-12, 20-27, and 35-36 (Group II) for prosecution in this application without traverse.

The Commissioner is hereby authorized to charge any additional fees which may be required in this application under 37 C.F.R. §§1.16-1.17 or credit any overpayment, to Deposit Account No. 13-0201. Should no proper payment be enclosed herewith, as by a check being in the wrong amount, unsigned, postdated, otherwise improper or informal or even entirely missing, the Commissioner is authorized to charge the unpaid amount to Deposit Account No. 13-0201. This sheet is filed in duplicate.

Respectfully submitted,

James W. Drapinski

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